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DATE MAILED: 07/25/2002

APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
09/768,174	01/24/2001	Toshiyuki Motooka	980100A	1934
23850 7	7590 07/25/2002			
ARMSTRON	09/768,174 01/24/2001 Toshiyuki Motooka 980100A 23850 7590 07/25/2002 ARMSTRONG,WESTERMAN & HATTORI, LLP 1725 K STREET, NW. SUITE 1000 WASHINGTON, DC. 20006	INER		
SUITE 1000		, JAMES M		
WASHINGTO			ART UNIT	PAPER NUMBER
			2827	\(\frac{1}{2}\)

Please find below and/or attached an Office communication concerning this application or proceeding.

	Application No.	Applicant(s)			
•	Application No.				
Office Action Summany	09/768,174	MOTOOKA ET AL.			
Office Action Summary	Examiner	Art Unit			
The MAILING DATE of this communication ap	James Mitchell	2827			
Period for Reply	pears on the cover sheet w	un the correspondence address			
A SHORTENED STATUTORY PERIOD FOR REPL THE MAILING DATE OF THIS COMMUNICATION. - Extensions of time may be available under the provisions of 37 CFR 1. after SIX (6) MONTHS from the mailing date of this communication. - If the period for reply specified above is less than thirty (30) days, a rep - If NO period for reply is specified above, the maximum statutory period - Failure to reply within the set or extended period for reply will, by statut - Any reply received by the Office later than three months after the mailir earned patent term adjustment. See 37 CFR 1.704(b). Status	136(a). In no event, however, may a light within the statutory minimum of thir will apply and will expire SIX (6) MON e. cause the application to become Al	reply be timely filed ty (30) days will be considered timely. ITHS from the mailing date of this communication. BANDONED (35 U.S.C. § 133).			
1) Responsive to communication(s) filed on <u>03</u>	<u> April 2002</u> .				
2a)⊠ This action is FINAL . 2b)⊡ T	his action is non-final.				
Since this application is in condition for allow closed in accordance with the practice under Disposition of Claims	rance except for formal ma Ex parte Quayle, 1935 C.	tters, prosecution as to the merits is D. 11, 453 O.G. 213.			
4)⊠ Claim(s) <u>11-17</u> is/are pending in the applicati	on.				
4a) Of the above claim(s) is/are withdrawn from consideration.					
5)⊠ Claim(s) <u>16 and 17</u> is/are allowed.					
6)⊠ Claim(s) <u>11-15</u> is/are rejected.					
7) Claim(s) is/are objected to.	7) Claim(s) is/are objected to.				
8) Claim(s) are subject to restriction and/	or election requirement.				
Application Papers					
9)☐ The specification is objected to by the Examiner.					
10) The drawing(s) filed on is/are: a) acc					
Applicant may not request that any objection to t					
11)☐ The proposed drawing correction filed on is: a)☐ approved b)☐ disapproved by the Examiner.					
If approved, corrected drawings are required in reply to this Office action.					
12) The oath or declaration is objected to by the Examiner.					
Priority under 35 U.S.C. §§ 119 and 120					
13) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).					
a) All b) Some * c) None of:					
 Certified copies of the priority documents have been received. 					
2. Certified copies of the priority documents have been received in Application No					
3. Copies of the certified copies of the pri application from the International B * See the attached detailed Office action for a lis	Bureau (PCT Rule 17.2(a)).				
14) Acknowledgment is made of a claim for domestic priority under 35 U.S.C. § 119(e) (to a provisional application).					
a) ☐ The translation of the foreign language p 15)⊠ Acknowledgment is made of a claim for dome	rovisional application has l	been received.			
Attachment(s)					
1) Notice of References Cited (PTO-892) 2) Notice of Draftsperson's Patent Drawing Review (PTO-948) 3) Information Disclosure Statement(s) (PTO-1449) Paper No(s)	5) Notice o	v Summary (PTO-413) Paper No(s) f Informal Patent Application (PTO-152)			

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DETAILED ACTION

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1. This office action is in response to the amendment filed April 3, 2002.

Claim Rejections - 35 USC § 102

2. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

- (e) the invention was described in a patent granted on an application for patent by another filed in the United States before the invention thereof by the applicant for patent, or on an international application by another who has fulfilled the requirements of paragraphs (1), (2), and (4) of section 371(c) of this title before the invention thereof by the applicant for patent.
- 3. Claims 11-13,15 and 16 are rejected under 35 U.S.C. 102(e) as being anticipated by Heo et. al. (U.S. 5,858,815).
- 4. Heo discloses a chip (11) having a top surface and a first electrode (12) with a polyimide resin (Lines 11-12, Column 5) circuit substrate (26) and a conductor pattern (26) including a second electrode (via the pad region of said pattern that is connected to a bond wire) formed thereon attached to the top of said chip, an adhesive resin (30) intervening between a top surface of said chip and said substrate, a spherical electrode (Fig. 11a, Item 24) on said substrate in correspondence to a third electrode, a bonding wire (Fig. 4b, Item 40) electrically interconnecting said second electrode on said conductor pattern and said first electrode on said chip, a potting (50) resin (Lines 19-22, Column 5) of the same material as the adhesive wherein said resin encapsulates said wire and said first and second electrode, the chip and potting defined by a common edge surface substantially perpendicular to a principal surface of said substrate with the resin potting including a sidewall portion that covers a sidewall of said

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circuit substrate (see Fig.6B); a polyimide layer (22; Column 5, Lines 10-12) which is inherently nonwettable and therefore is a solder resist material formed on said circuit substrate, wherein spherical electrode (60) are formed in an opening in said solder resist layer.

Claim Rejections - 35 USC § 103

- 5. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
 - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 6. Claim 14 is rejected under 35 U.S.C. 103(a) as being unpatentable over Heo as applied to claim 11 and further in view of Nakamura (U.S. 5,729,051).
- 7. Heo does not show a circuit substrate comprising a glass epoxy, however Nakamura utilizes a glass epoxy circuit substrate (Fig.1).
- 8. It would have been obvious to one of ordinary skill in the art to form the circuit substrate of Heo with a glass epoxy, since the use of glass epoxy for a substrate is conventional in the manufacture of a Ball Grid Array (BGA) as taught by Nakamura (Lines 50-53, Column 1).

Response to Arguments

9. Applicant's arguments with respect to claims 11-15 have been considered but are most in view of the new explanation in the rejection and new grounds of rejection.

Allowable Subject Matter

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- 10. Claims 16 and 17 are allowed. The following is an examiner's statement of reasons for allowance: The prior art does not disclose or make obvious a semiconductor device comprising a resin potting filling a space between a chip and a circuit substrate with bonding wires on said chip connected to electrodes on said circuit substrate wherein the chip sidewall is flush to the outer surface of the resin side wall.
- 11. Any comments considered necessary by applicant must be submitted no later than the payment of the issue fee and, to avoid processing delays, should preferably accompany the issue fee. Such submissions should be clearly labeled "Comments on Statement of Reasons for Allowance."

Conclusion

12. Applicant's amendment necessitated the new ground(s) of rejection presented in this Office action. Accordingly, **THIS ACTION IS MADE FINAL**. See MPEP § 706.07(a). Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the date of this final action.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to James Mitchell whose telephone number is (703) 305-0244. The examiner can normally be reached on M-F 10:30-8:00.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, David L. Talbott can be reached on (703) 305-9883. The fax phone numbers for the organization where this application or proceeding is assigned are (703) 305-3432 for regular communications and (703) 305-3230 for After Final communications.

Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the receptionist whose telephone number is (703) 308-0956.

jmm

July 1, 2002

Y KAMAND CUNEO PRIMARY EXAMINER